

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT8044143

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHING-SHAN LIN	06/27/2023
YE-JUN WANG	06/27/2023
CHIEN-CHENG LIOU	06/27/2023
RECEIVING PARTY DATA	
Name:	GLOBALWAFERS CO., LTD.
Street Address:	NO. 8, INDUSTRIAL EAST ROAD 2, SCIENCE-BASED INDUSTRIAL PARK,
City:	HSINCHU
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18344867
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	123728-US-PA
NAME OF SUBMITTER:	DANIEL HSIEH
SIGNATURE:	/Daniel Hsieh/
DATE SIGNED:	07/06/2023
Total Attachments: 2	
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ASSIGNMENT

WHEREAS,

1.Ching-Shan Lin
3.Chien-Cheng Liou

2.Ye-Jun Wang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **CRYSTAL GROWTH METHOD AND WAFER**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, 1. GlobalWafers Co., Ltd.
of No. 8, Industrial East Road 2, Science-Based Industrial
Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ching-Shan Lin Date: June 27, 2023
Sole or First Joint Inventor: **Ching-Shan Lin**

Signature: Ye-Jun Wang Date: June 27, 2023
Second Joint Inventor (if any): **Ye-Jun Wang**

Signature: Chien-Cheng Liou Date: June 27, 2023
Third Joint Inventor (if any): **Chien-Cheng Liou**